MOS FET

MTM861270LBF

Panasonic

MTM861270LBF

Silicon P-channel MOSFET

For Switching

■ Features

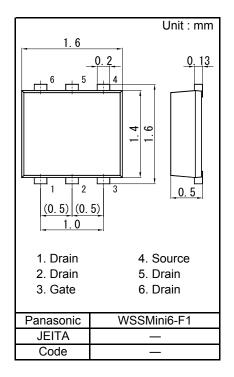
- Low drain-source On-state Resistance : RDS(on) typ = 80 m Ω (VGS = -4 V)
- Low drive voltage: 1.8 V drive
- Halogen-free / RoHS compliant

(EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)

■ Marking Symbol : MK

■ Packaging

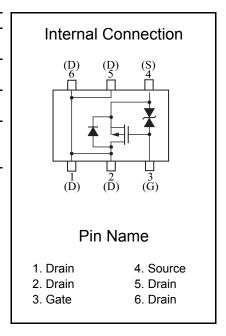
Embossed type (Thermo-compression sealing): 10 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit	
Drain to Source Voltage	VDS	-20	V	
Gate to Source Voltage	VGS	±10	V	
Drain Current	ID	-2	Α	
Drain Current (Pulsed) *1	IDp	-8		
Total Power Dissipation	PD1 *2	540	mW	
	PD2 *3	150	11177	
Channel Temperature	Tch	150		
Operating Ambient Temperature	Topr	-40 to +85	°C	
Storage Temperature Range	Tstg	-55 to +150		

- Note) *1 $t \le 10 \mu s$, Duty cycle $\le 1 \%$
 - *2 Glass epoxy substrate (25.4 \times 25.4 \times t 0.8 mm) coated with copper foil (more than 300 mm 2)
 - *3 Non-heat sink



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■ Electrical Characteristics Ta = 25 °C ± 3 °C

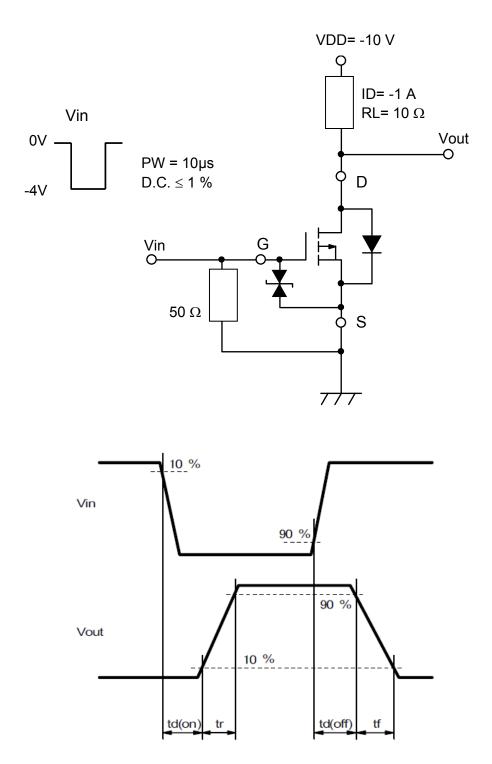
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Drain-source Breakdown Voltage	VDSS	ID = -1 mA, VGS = 0 V	-20			V	
Zero Gate Voltage Drain Current	IDSS	VDS = -20 V, VGS = 0 V			-1	۸	
Gate-source Leakage Current	IGSS	$VGS = \pm 8 \text{ V}, VDS = 0 \text{ V}$			±10	μΑ	
Gate-source Threshold Voltage	Vth	ID = -1 mA, VDS = -10 V	-0.4	-0.75	-1.1	V	
Drain-source On-state Resistance *1	RDS(on)1	ID = -1 A, VGS = -4 V		80	120	mΩ	
	RDS(on)2	ID = -1 A, VGS = -2.5 V		100	170		
	RDS(on)3	ID = -0.5 A, VGS = -1.8 V		140	230		
Forward transfer admittance *1	Yfs	ID = -1 A, VDS = -10 V, f = 1 kHz	3			S	
Input Capacitance	Ciss	VDS = -10 V, VGS = 0 V		300		pF	
Output Capacitance	Coss	f = 1 MHz		30			
Reverse Transfer Capacitance	Crss	1 = 1 MHZ		35			
Turn-on Delay Time *2	td(on)	VDD = -10 V, VGS = 0 to -4 V		6			
Rise Time *2	tr	ID = -1 A		8		no	
Turn-off Delay Time *2	td(off)	VDD = -10 V, VGS = -4 to 0 V		57		ns	
Fall Time *2	tf	ID = -1 A		55			

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

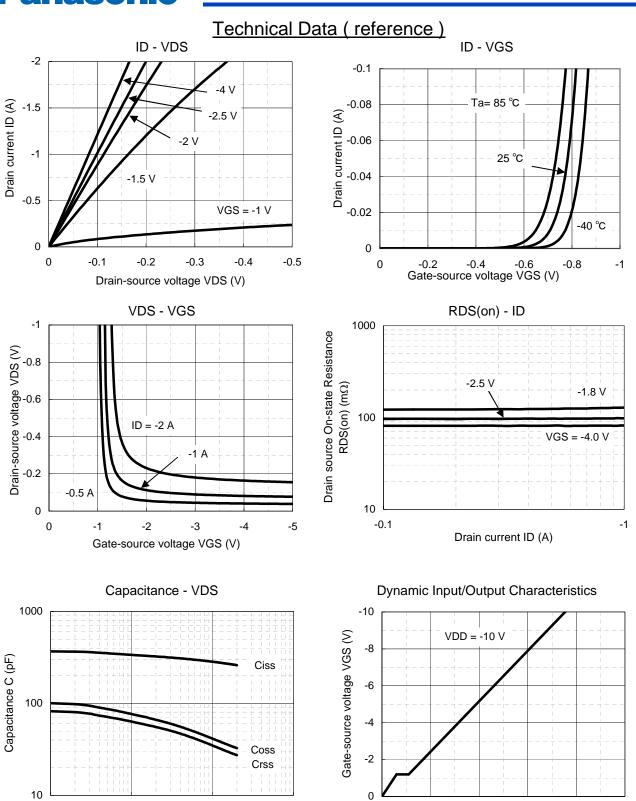
^{*1} Pulse test

^{*2} Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



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-100

0

2

4

Total Gate Charge Qg (nC)

-10

Drain-source voltage VDS (V)

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10

8

Established: 2008-01-09 Revised: 2013-10-10

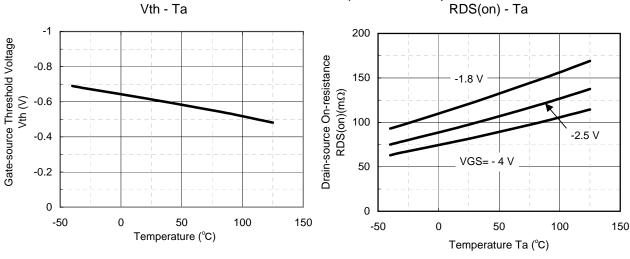
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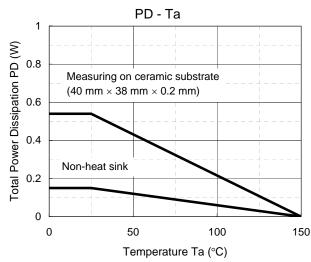
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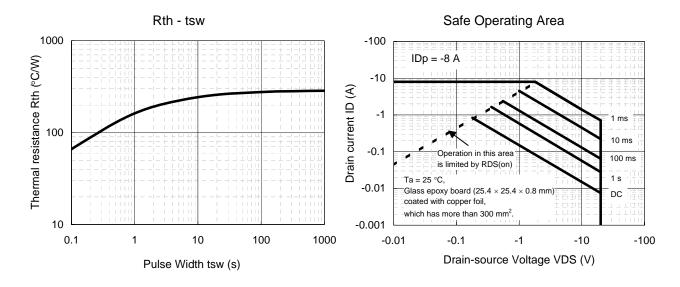
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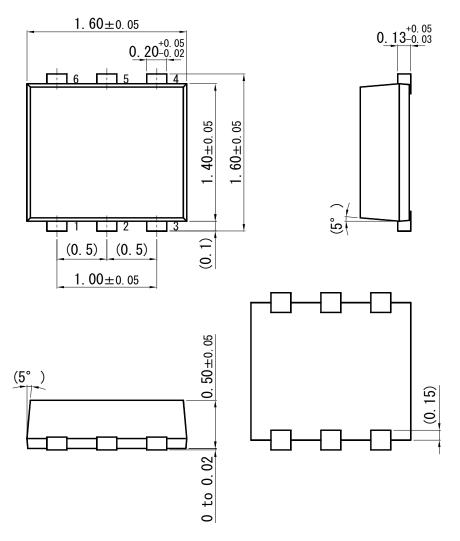




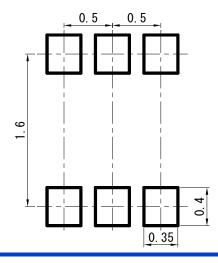
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WSSMini6-F1

Unit: mm



■ Land Pattern (Reference) (Unit : mm)



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